

**SN74AC244**

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| SHEREL.95.ACL.11115 | **SN74AC244 ESD** |  |  |
| **Device:**  | SN74AC244 | **Die Rev:**  | A |  |  |
| **Technology:**  | CMOS |  |  |  |  |

|  |  |  |  |
| --- | --- | --- | --- |
| **Test Type** | **Voltage** | **Qty** | **Fails** |
| ESD - HBM | 500 V | 3 | 0 |
|  | 1000 V | 3 | 0 |
|  | 1500 V | 3 | 0 |
|  | 2000 V | 3 | 0 |
|  |  |  |  |
| ESD - MM | 50 V | 3 | 0 |
|  | 100 V | 3 | 0 |
|  | 150 V | 3 | 0 |
|  | 200 V | 3 | 0 |
|  |  |  |  |
| ESD - CDM | 250 V | 3 | 0 |
|  | 500 V | 3 | 0 |
|  | 750 V | 3 | 0 |
|  | 1000 V | 3 | 0 |

**Wafer Fabrication Process Family Reliability Testing Data**

The following data is for testing completed on various part number devices with die fabricated using the same die fabrication process as the subject part number device. This data is not specific to the subject device.

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| --- | --- | --- | --- |
| **Test** | **Conditions** | **Quantity Tested** | **Failures** |
| AUTOCLAVE | 15 psig, 121 Degrees C,96 Hours | 1652 | 0Top of Form |
| HAST | 130 Degrees C / 85 % RH with bias,96 Hours | 1155 | 0Top of Form |
| LIFE TEST | 125C,1000 Hours | 630 | 0Top of Form |
| TEMP CYCLE | -65 / +150 Degrees C,1000 Cycles | 1155 | 0Top of Form |
| THERMAL SHOCK | -65 / +150 Degrees C,1000 Cycles | 231 | 0Bottom of FormBottom of FormBottom of FormBottom of Form |

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Reliability data shows characteristic failure mechanisms of the specific environmental stress as documented in the industry standards for each stress condition.

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